POWER-MOS FET
FIELD EFFECT POWER TRANSISTOR

IRFD210,211
D82BN2,M2

0.6 AMPERES
200, 150 VOLTS
$R_{DS(ON)}$ = 1.5 Ω

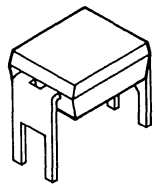
This series of N-Channel Enhancement-mode Power MOSFETs utilizes GE's advanced Power DMOS technology to achieve low on-resistance with excellent device ruggedness and reliability.

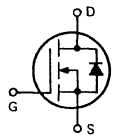
This design has been optimized to give superior performance in most switching applications including: switching power supplies, inverters, converters and solenoid/relay drivers. Also, the extended safe operating area with good linear transfer characteristics makes it well suited for many linear applications such as audio amplifiers and servo motors.

Features

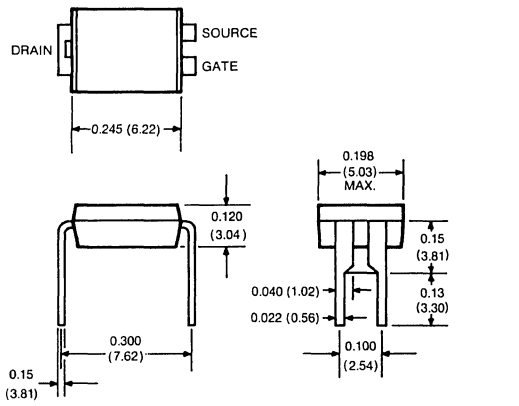
- Polysilicon gate — Improved stability and reliability
- No secondary breakdown — Excellent ruggedness
- Ultra-fast switching — Independent of temperature
- Voltage controlled — High transconductance
- Low input capacitance — Reduced drive requirement
- Excellent thermal stability — Ease of paralleling

N-CHANNEL





CASE STYLE 4-PIN DIP
DIMENSIONS ARE IN INCHES AND (MILLIMETERS)



maximum ratings (T_A = 25°C) (unless otherwise specified)

RATING	SYMBOL	IRFD210/D82BN2	IRFD211/D82BM2	UNITS
Drain-Source Voltage	V_{DSS}	200	150	Volts
Drain-Gate Voltage, R_{GS} = 1MΩ	V_{DGR}	200	150	Volts
Continuous Drain Current @ T_A = 25°C(1) @ T_A = 100°C(1)	I_D	0.6 0.35	0.6 0.35	A A
Pulsed Drain Current(2)	I_{DM}	2.5	2.5	A
Gate-Source Voltage	V_{GS}	±20	±20	Volts
Total Power Dissipation @ T_A = 25°C Derate Above 25°C	P_D	1.0 8	1.0 8	Watts mW/°C
Operating and Storage Junction Temperature Range	T_J, T_{STG}	-55 to 150	-55 to 150	°C

thermal characteristics

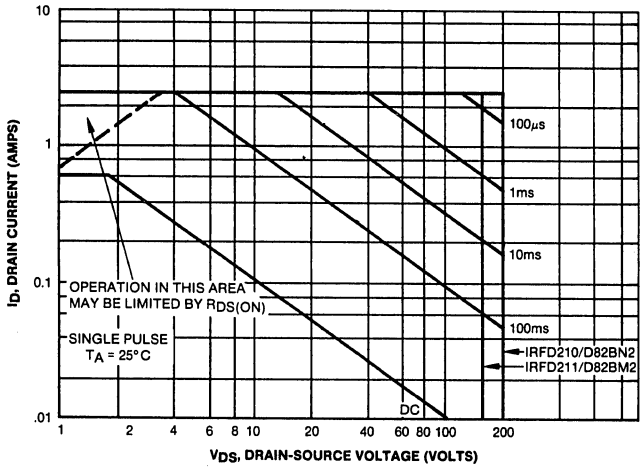
Thermal Resistance, Junction to Ambient(1)	$R_{\theta JA}$	125	125	°C/W
Maximum Lead Temperature for Soldering Purposes: ⅛" from Case for 5 Seconds	T_L	300	300	°C

(1) Device mounted to vertical pc board in free air with drain lead soldered to 0.20 in^2 minimum copper run area.
(2) Repetitive Rating: Pulse width limited by max. junction temperature.

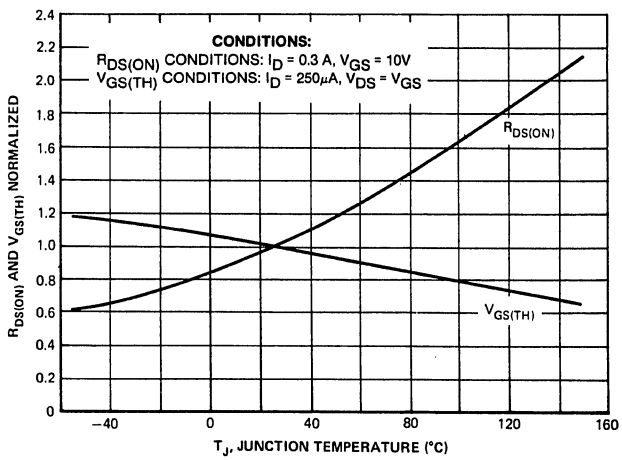
electrical characteristics (T_A = 25°C) (unless otherwise specified)

CHARACTERISTIC		SYMBOL	MIN	TYP	MAX	UNIT
off characteristics						
Drain-Source Breakdown Voltage (V_{GS} = 0V, I_D = 250 μA)	IRFD210/D82BN2 IRFD211/D82BM2	BV_{DSS}	200 150	— —	— —	Volts
Zero Gate Voltage Drain Current (V_{DS} = Max Rating, V_{GS} = 0V, T_A = 25°C) (V_{DS} = Max Rating, × 0.8, V_{GS} = 0V, T_A = 125°C)		I_{DSS}	— —	— —	250 1000	μA
Gate-Source Leakage Current (V_{GS} = ±20V)		I_{GSS}	—	—	±500	nA
on characteristics*						
Gate Threshold Voltage (V_{DS} = V_{GS}, I_D = 250 μA)	T_A = 25°C	$V_{GS(TH)}$	2.0	—	4.0	Volts
On-State Drain Current (V_{GS} = 10V, V_{DS} = 10V)		$I_{D(ON)}$	0.6	—	—	A
Static Drain-Source On-State Resistance (V_{GS} = 10V, I_D = 0.3A)		$R_{DS(ON)}$	—	1.1	1.5	Ohms
Forward Transconductance (V_{DS} = 10V, I_D = 0.3A)		g_{fs}	0.35	0.4	—	mhos
dynamic characteristics						
Input Capacitance	V_{GS} = 0V	C_{iss}	—	120	150	pF
Output Capacitance	V_{DS} = 25V	C_{oss}	—	40	80	pF
Reverse Transfer Capacitance	f = 1 MHz	C_{rss}	—	10	25	pF
switching characteristics*						
Turn-on Delay Time	V_{DS} = 90V	$t_{d(on)}$	—	5	—	ns
Rise Time	I_D = 0.3A, V_{GS} = 15V	t_r	—	15	—	ns
Turn-off Delay Time	R_{GEN} = 50Ω, R_{GS} = 12.5Ω	$t_{d(off)}$	—	10	—	ns
Fall Time	($R_{GS\ (EQUIV.)}$ = 10Ω)	t_f	—	10	—	ns
source-drain diode ratings and characteristics*						
Continuous Source Current		I_S	—	—	0.60	A
Pulsed Source Current		I_{SM}	—	—	2.5	A
Diode Forward Voltage (T_A = 25°C, V_{GS} = 0V)	I_S = 0.60A	V_{SD}	—	0.8	2.0	Volts
Reverse Recovery Time (I_S = 0.6A, di_S/dt = 100A/μs, T_A = 125°C)		t_{rr} Q_{RR}	— —	100 0.75	— —	ns μC

*Pulse Test: Pulse width ≤ 300 μs, duty cycle ≤ 2%



MAXIMUM SAFE OPERATING AREA



TYPICAL NORMALIZED $R_{DS(ON)}$ AND $V_{GS(TH)}$ VS. TEMP.